

SOT-23 Plastic-Encapsulate MOSFETS

N-Channel MOSFET

FEATURE

- Surface Mount Package
- High Density Cell Design for Extremely Low $R_{DS(ON)}$
- Voltage Controlled Small Signal Switch
- Rugged and Reliable

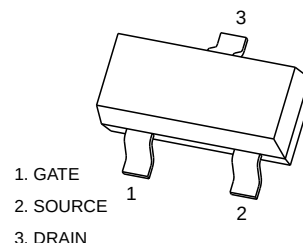
APPLICATION

- Small Servo Motor Controls
- Power MOSFET Gate Drivers
- Switching Application

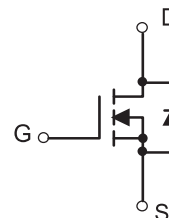
MARKING



SOT-23



Equivalent Circuit



$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
100V	$6\Omega@10V$	0.17A
	$10\Omega@4.5V$	

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
N-MOSFET			
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (note 1)	I_D	0.17	A
Pulsed Drain Current ($t_p=10\mu s$)	I_{DM}	0.68	A
Continuous Source-Drain Diode Current	I_S	0.17	A
Power Dissipation	P_D	0.35	W
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	357	$^\circ C/W$
Operation Junction and Storage Temperature Range	T_J, T_{STG}	$-55 \sim +150$	$^\circ C$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	$^\circ C$

MOSFET ELECTRICAL CHARACTERISTICS

T_a=25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	100			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V,V _{GS} = 0V			1	μA
		V _{DS} =20V,V _{GS} = 0V			10	nA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±50	nA
Gate threshold voltage (note 2)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.6	2	V
Drain-source on-resistance(note 2)	R _{DS(on)}	V _{GS} =4.5V, I _D =0.17A		3.8	10	Ω
		V _{GS} =10V, I _D =0.17A		3.5	6	Ω
Forward tranconductance(note 2)	g _{FS}	V _{DS} =10V, I _D =170mA	80			mS
Diode forward voltage	V _{SD}	I _S =340mA, V _{GS} = 0V			1.3	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V,f =1MHz		29	60	pF
Output Capacitance	C _{oss}			10	15	pF
Reverse Transfer Capacitance	C _{rss}			2	6	pF
SWITCHING CHARACTERISTICS (note 3,4)						
Turn-on delay time	t _{d(on)}	V _{GS} =10V,V _{DD} =30V, I _D =0.28A,R _{GEN} =50 Ω			8	ns
Turn-on rise time	t _r				8	ns
Turn-off delay time	t _{d(off)}				13	ns
Turn-off fall time	t _f				16	ns
Total Gate Charge	Q _g	V _{DS} =10V,I _D =0.22A, V _{GS} =10V		1.4	2	nC
Gate-Source Charge	Q _{gs}			0.15	0.25	nC
Gate-Drain Charge	Q _{gd}			0.2	0.4	nC

Notes :

- 1.Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300μs, duty cycle≤2%.
3. Switching characteristics are independent of operating junction temperature.
4. Granted by design, not subject to producing.

Typical Characteristics

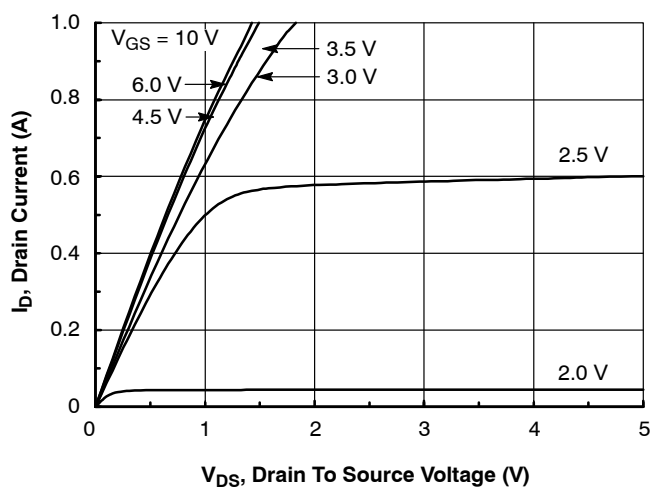


Figure 1. On-Region Characteristics

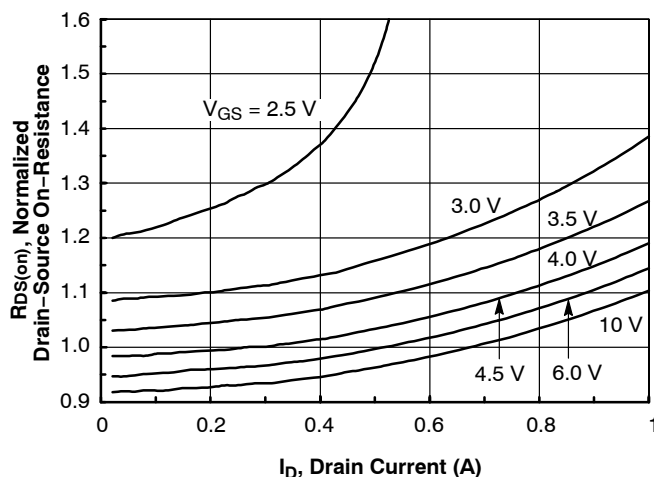


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

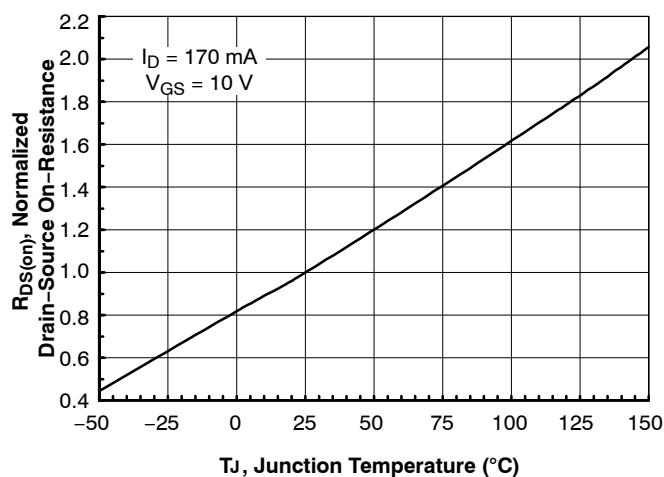


Figure 3. On-Resistance Variation with Temperature

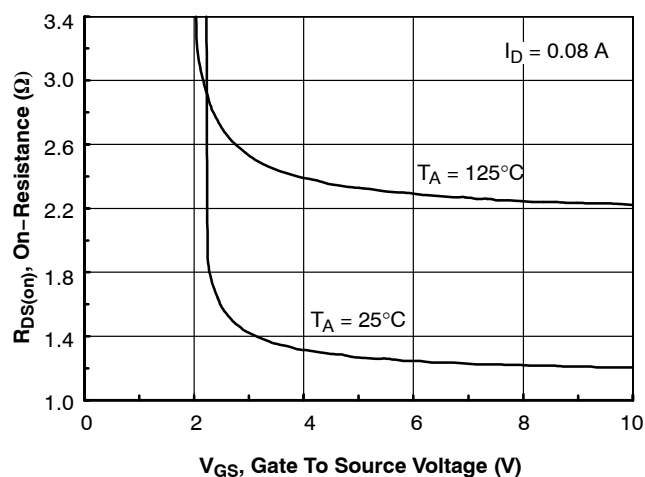


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

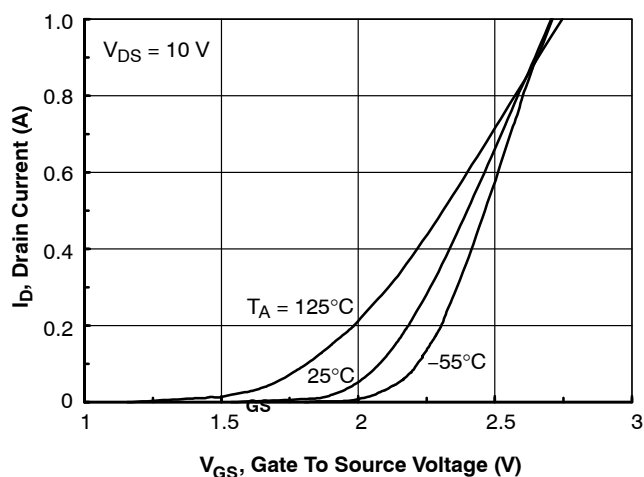


Figure 5. Transfer Characteristics

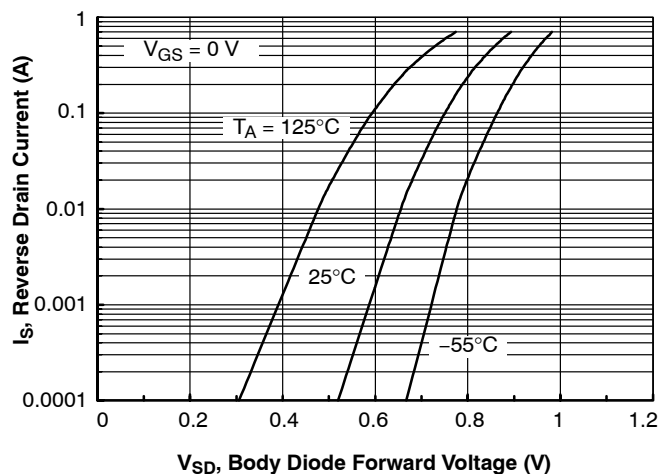


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics

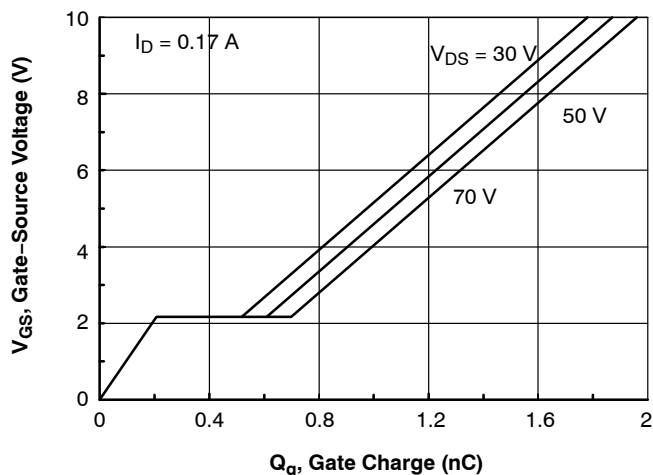


Figure 7. Gate Charge Characteristics

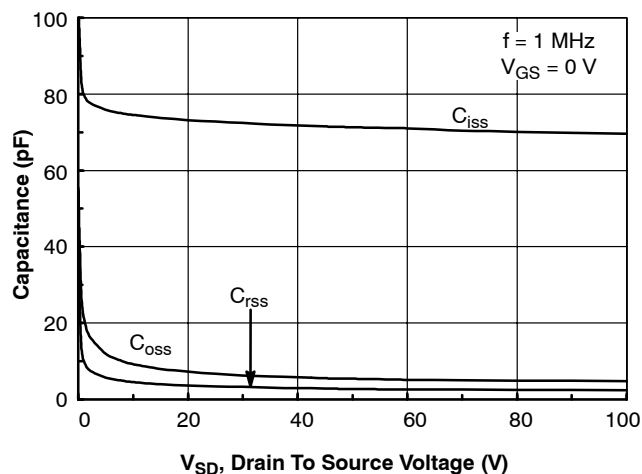


Figure 8. Capacitance Characteristics

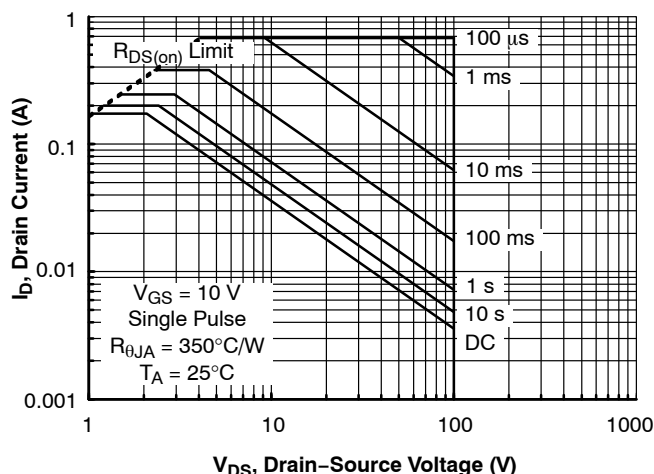


Figure 9. Maximum Safe Operating Area

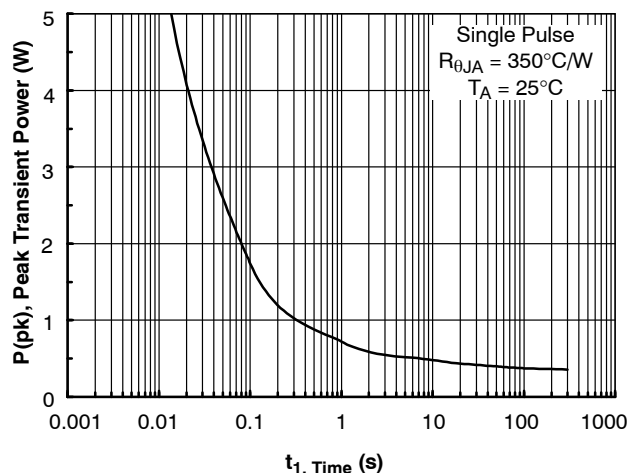


Figure 10. Single Pulse Maximum Power Dissipation

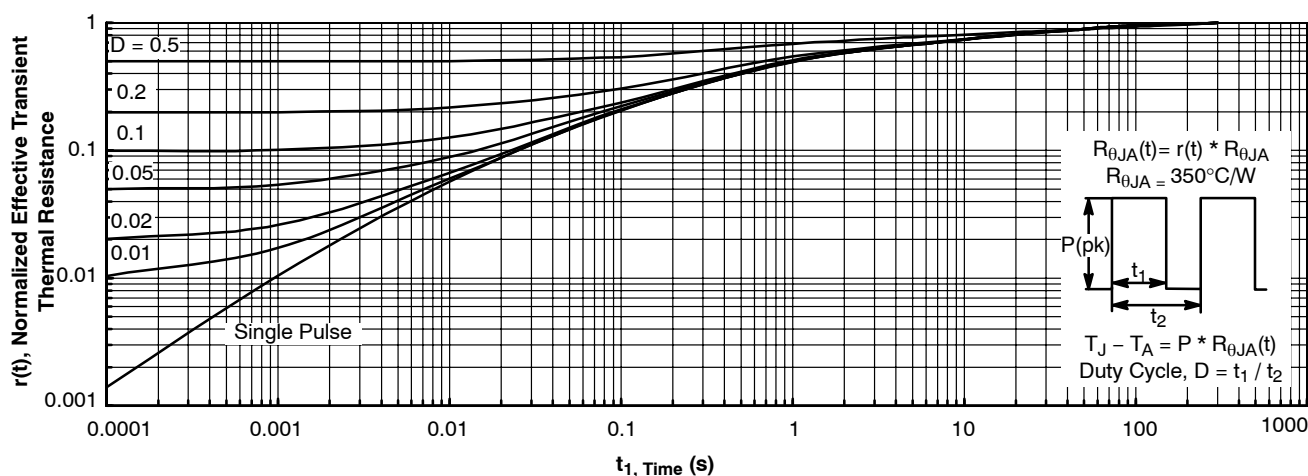
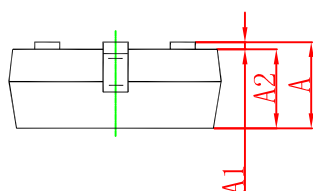
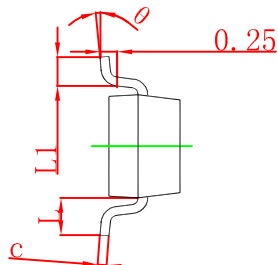
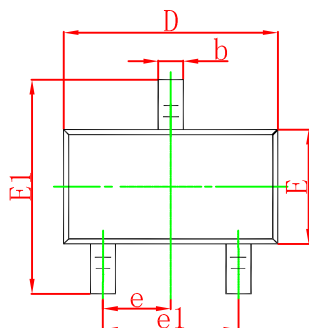


Figure 11. Transient Thermal Response Curve

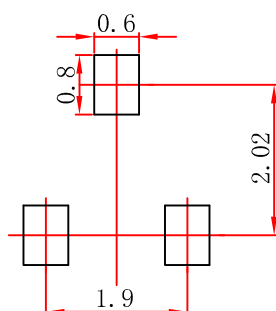
Thermal characterization performed using the conditions described in Note 1a.
Transient thermal response will change depending on the circuit board design.

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



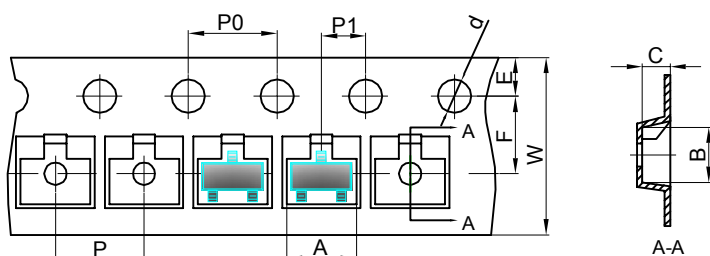
Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

SOT-23 Tape and Reel

SOT-23 Tape and reel

SOT-23 Embossed Carrier Tape

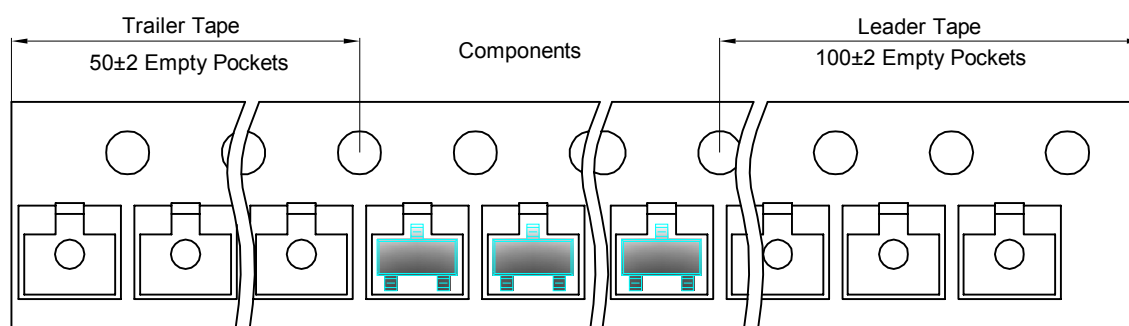


Packaging Description:

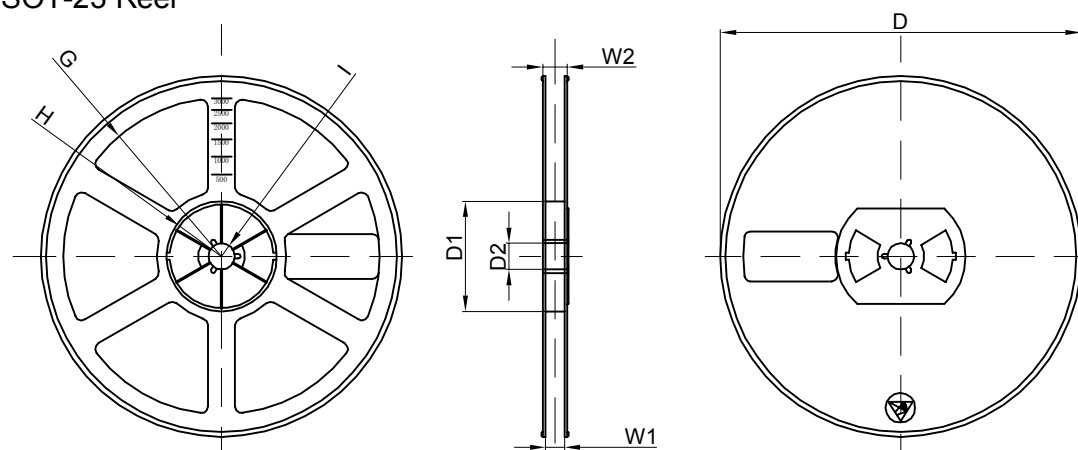
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 17.8cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23 Tape Leader and Trailer



SOT-23 Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7"Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	45,000 pcs	203×203×195	180,000 pcs	438×438×220	